

IGBT

Features

- 600V,20A
- $V_{CE(sat)(typ.)}$ =1.85V@ V_{GE} =15V, I_{C} =20A
- High speed switching
- Higher system efficiency
- Soft current turn-off waveforms



JIAEN trench IGBTs offer lower losses and higher energy efficiency for application such as PFC, UPS, general inverter and other soft switching applications.





Absolute Maximum Ratings

Symbol	Parameter	Value	Units
V _{CES}	Collector-Emitter Voltage	600	V
V _{GES}	Gate-Emitter Voltage	<u>+</u> 20	V
lc	Continuous Collector Current (T _C =25 °C)	40	Α
	Continuous Collector Current (Tc=100°C)	20	А
I _{CM}	Pulsed Collector Current (Note 1)	60	А
I _F	Diode Continuous Forward Current (T _C =100 °C)	20	А
I _{FM}	Diode Maximum Forward Current (Note 1)	60	А
t _{sc}	Short Circuit Withstand Time	10	us
P _D	Maximum Power Dissipation (Tc=25°C)	26	W
	Maximum Power Dissipation (Tc=100°C)	10	W
TJ	Operating Junction Temperature Range	-55 to +150	°C
Тѕтс	Storage Temperature Range	-55 to +150	℃

Thermal Characteristics

Symbol	Parameter	Max.	Units
R _{th j-c}	Thermal Resistance, Junction to case for IGBT	4.8	°C/ W
R _{th j-c}	Thermal Resistance, Junction to case for Diode	6.9	°C/ W
R _{th j-a}	Thermal Resistance, Junction to Ambient	65	°C/ W



Electrical Characteristics (Tc=25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
BV _{CES}	Collector-Emitter Breakdown Voltage	V_{GE} = 0V, I_{C} = 250uA	600	-	-	V
I _{CES}	Collector-Emitter Leakage Current	V _{CE} = 600V, V _{GE} = 0V	-	-	100	uA
	Gate Leakage Current, Forward	V_{GE} =20V, V_{CE} = 0V	-	-	200	nA
I _{GES}	Gate Leakage Current, Reverse	V_{GE} = -20V, V_{CE} = 0V	-	-	-200	nA
$V_{GE(th)}$	Gate Threshold Voltage	$V_{GE} = V_{CE}$, $I_{C} = 250uA$	4.5	-	6.5	V
$V_{\text{CE(sat)}}$	Collector-Emitter Saturation Voltage	V _{GE} =15V, I _C = 15A	-	1.85	2.4	V
Qg	Total Gate Charge	Vcc=480V	-	60		nC
Qge	Gate-Emitter Charge	V _{GE} =15V	-	9		nC
Q _{gc}	Gate-Collector Charge	Ic=20A	-	25		nC
C _{ies}	Input Capacitance	V _{CE} =25V V _{GE} =0V f = 1MHz	-	1100	-	pF
C _{oes}	Output Capacitance		-	60	-	pF
C _{res}	Reverse Transfer Capacitance		-	34	-	pF
t _{d(on)}	Turn-on Delay Time	V _{cc} =400V V _{gE} =15V I _c =20A R _G =10Ω Inductive Load T _c =25 °C	-	31	-	ns
t r	Turn-on Rise Time		-	29	-	ns
t d(off)	Turn-off Delay Time		-	44	-	ns
t f	Turn-off Fall Time		-	35	-	ns
Eon	Turn-on Switching Loss		-	0.58	-	mJ
Eoff	Turn-off Switching Loss		-	0.2	-	mJ
Ets	Total Switching Loss		-	0.78	-	mJ

Electrical Characteristics of Diode (Tc=25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
V _F	Diode Forward Voltage	I _F =20A	ı	1.6	2.2	V
trr	Diode Reverse Recovery Time	V _{CE} = 300V		47		ns
Irr	Diode peak Reverse Recovery Current	I _F = 10A		7.5		Α
Qrr	Diode Reverse Recovery Charge	dl _F /dt = 100A/us	-	176		nC

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature



Typical Performance Characteristics

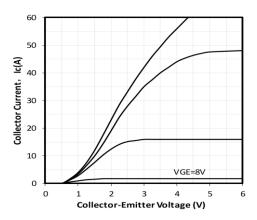


Fig 1. Output characteristics

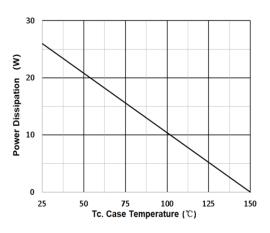


Figure 3. Power Dissipation vs. Tc

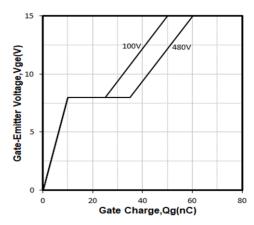


Figure 5. Gate Charge Characteristics

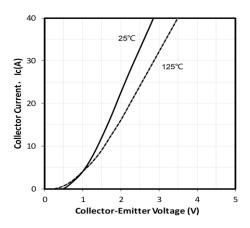


Fig 2. Typical Saturation Voltage Characteristics , V_{GE}=15V

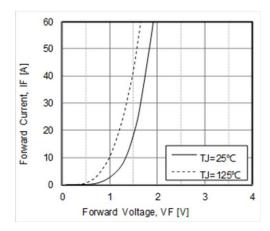


Figure 4. Forward Characteristics

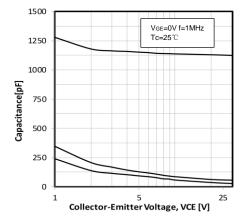


Figure 6. Capacitance Characteristics



Typical Performance Characteristics

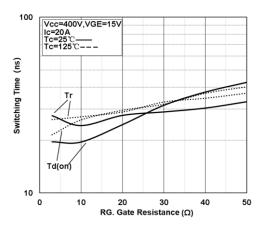


Figure 7. Turn-On Characteristics vs. Gate Resistance

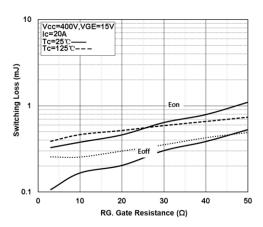


Figure 9. Switching Loss vs. Gate Resistance

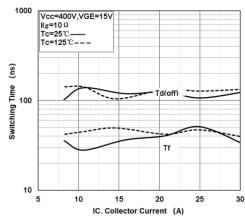


Figure 11. Turn-Off Characteristics vs. Collector Current

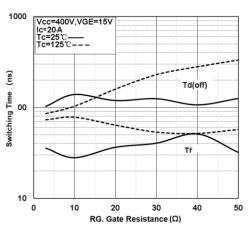


Figure 8. Turn-Off Characteristics vs. Gate Resistance

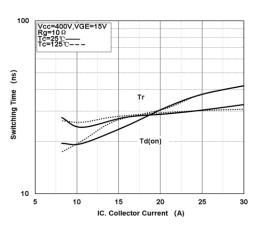


Figure 10. Turn-On Characteristics vs. Collector Current

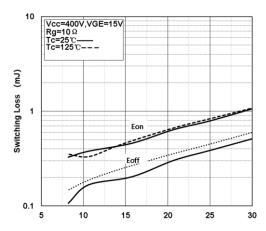


Figure 12. Switching Loss vs. Collector Current



Typical Performance Characteristics

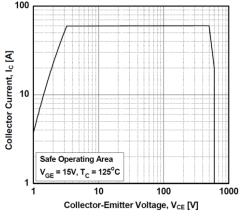


Figure 13. Turn-Off SOA

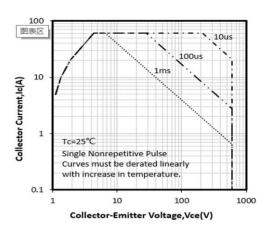


Figure 14. SOA Characteristics

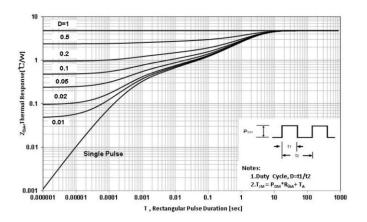
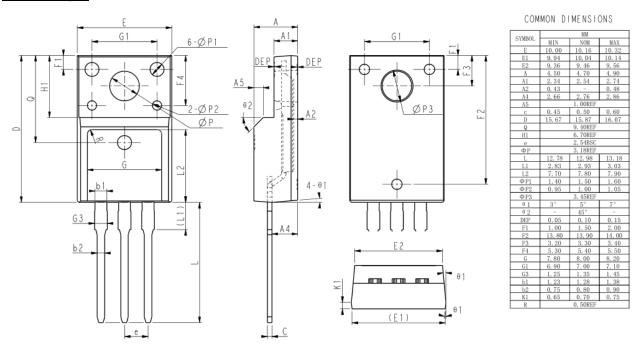


Figure 15. Transient Thermal Impedance of IGBT



Package



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